Specification of Thermoelectric Module

TEC4-69-29-11-6-035

Description

The TEC4-69-29-11-6-035 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 69-29-11-6 couples module in size of 14.5 mm×4.5 mm (top) / 33 mm ×24 mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

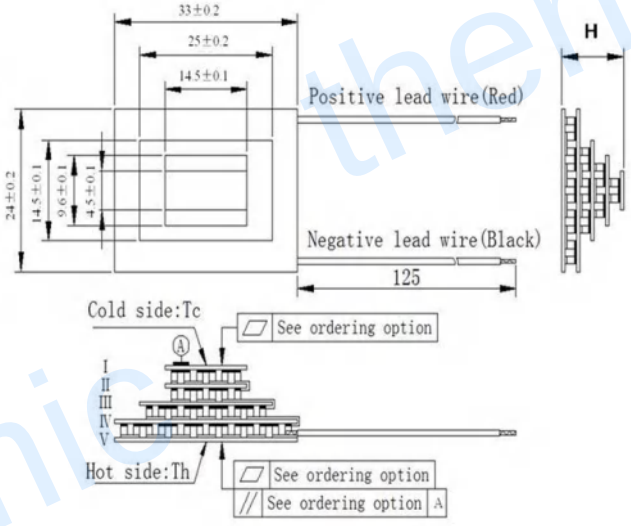
Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N_2
DT_{max} (°C)	116	129	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U_{max} (Voltage)	8.0	8.9	Voltage applied to the module at DT_{max}
I_{max} (Amps)	3.8	3.8	DC current through the modules at DT_{max}
Q_{Cmax} (Watts)	3.0	3.3	Cooling capacity at cold side of the module under DT=0°C
AC resistance (Ohms)	2.10	2.25	The module resistance is tested under AC
Tolerance	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138ºC)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al_2O_3, white 96%)
2. Aluminum Nitride (AlN)

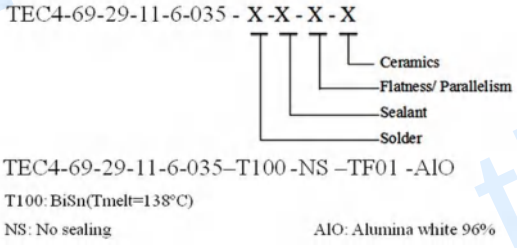
D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 13.4±0.3	0: 0.08/0.08	125±1/Specify
TF	1: 13.4±0.15	1:0.03/0.03	125±1/Specify
Eg. TF01: Thickness 13.4±0.3 (mm) and Flatness/ Parallelism ： 0.03/0.03(mm)			

Naming for the Module



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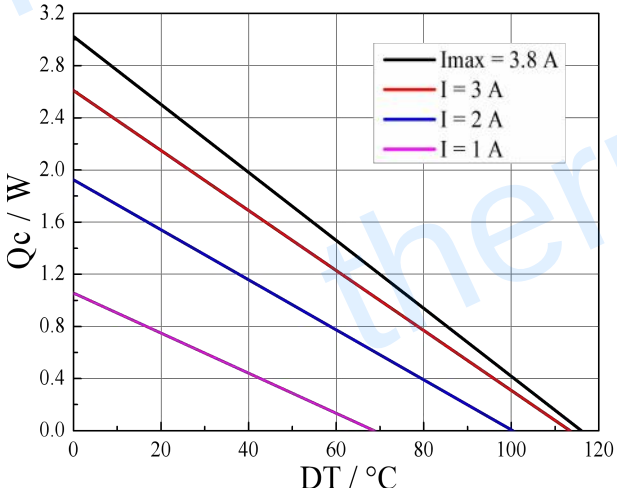
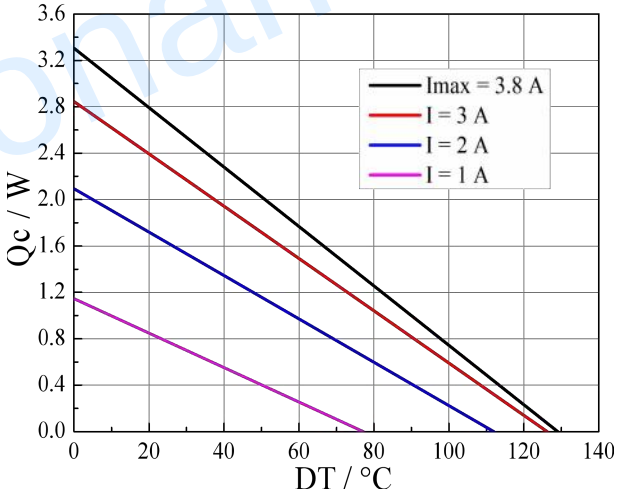
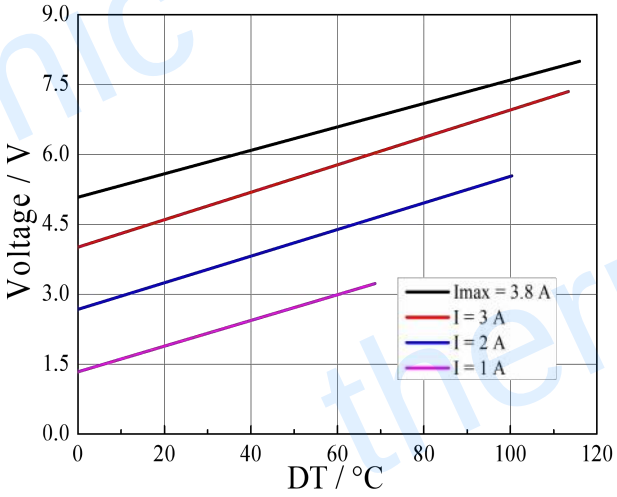
Performance Curves at Th=27 ºC

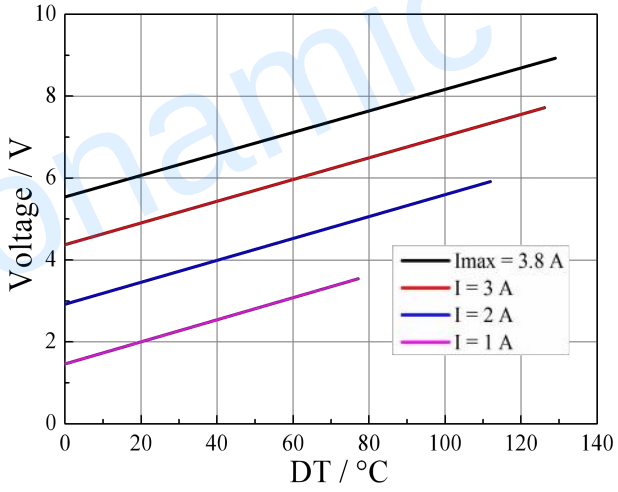


Performance Curves at Th=50 ºC

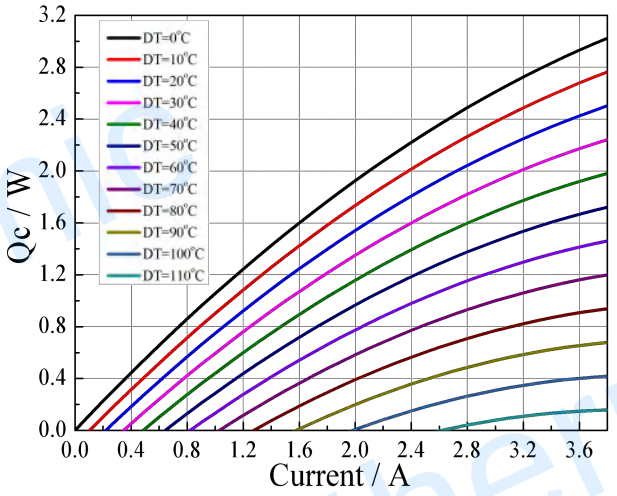


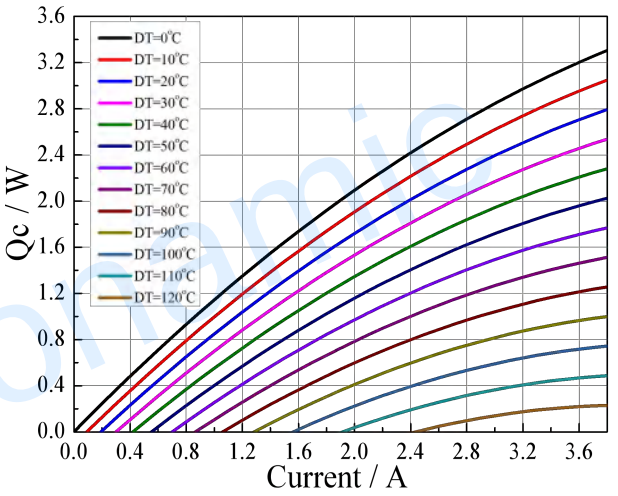
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





Standard Performance Graph Qc= f(I)

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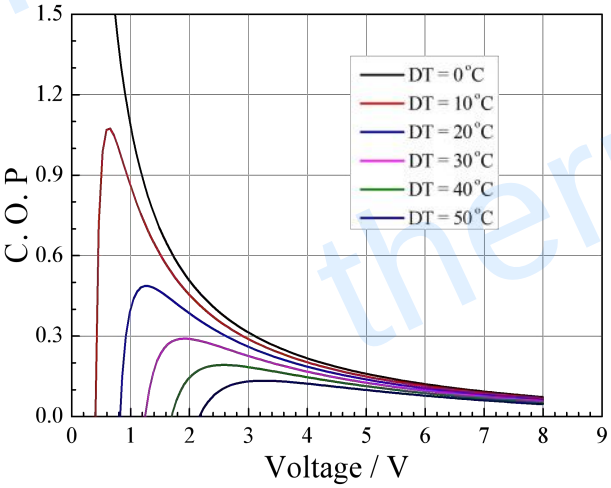
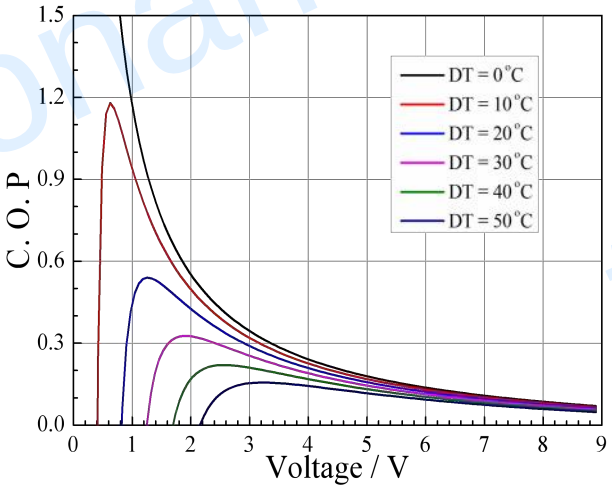
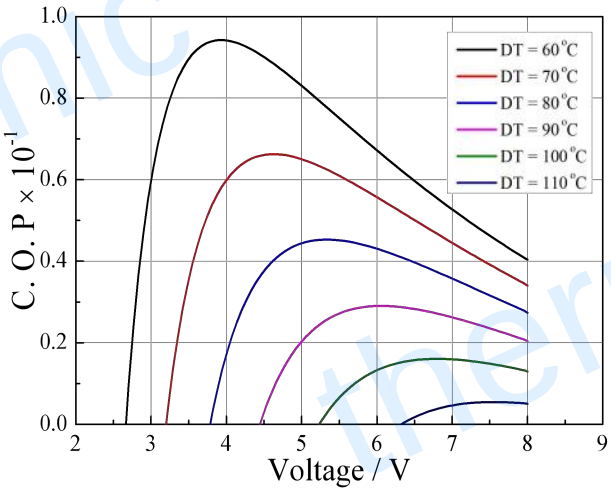
Performance Curves at Th=27 ºC

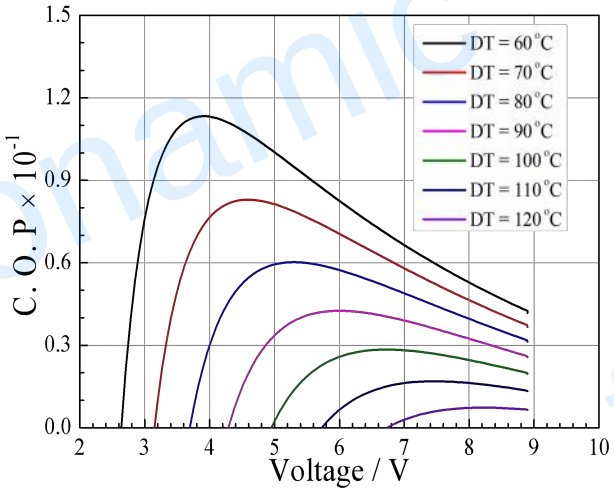


Performance Curves at Th=50 ºC



Standard Performance Graph COP = f(I) of DT ranged from 0 to 50 ˚C





Standard Performance Graph COP = f(V) of DT ranged from 60 to 110/120 ˚C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC